

## **IN THE SPECIFICATION**

Please replace the paragraph [0001] with the following paragraph:

[0001] This application is a continuation-in-part of co-pending United States Patent Application Serial No. 10/038,066, filed January 3, 2002, entitled "Planarization Of Substrates Using Electrochemical Mechanical Polishing" ~~[Attorney Docket No. 5699]~~, that claims priority to U.S. Provisional Patent Application Serial No. 60/275,874, filed on March 14, 2001, which claims priority to United States Provisional Patent Application Serial No. 60/275,874, filed on March 14, 2002, and a continuation-in-part of co-pending United States Patent Application Serial No. 10/032,275, filed December 21, 2001, entitled "Electrolyte Composition And Treatment For Electrolytic Chemical Mechanical Polishing" ~~[Attorney Docket No. 5998]~~, a continuation-in-part of co-pending United States Patent Application Serial No. 10/378,097, filed February 26, 2003, entitled "Method and Composition For Polishing a Substrate", which claims priority to United States Provisional Patent Application Serial No. 60/359,746, filed on February 26, 2002, and a continuation-in-part of co-pending United States Patent Application Serial No. 10/456,220, filed June 6, 2003, entitled "Method and Composition For Polishing a Substrate", which applications are incorporated by reference herein.